

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5568917

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	MERGER
<b>EFFECTIVE DATE:</b>	08/04/2017
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CSMC TECHNOLOGIES FAB1 CO., LTD.	08/31/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	CSMC TECHNOLOGIES FAB2 CO., LTD.
<b>Street Address:</b>	NO. 8 XINZHOU ROAD
<b>City:</b>	WUXI NEW DISTRICT, JIANGSU
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	214028
<b>PROPERTY NUMBERS Total: 6</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	13384002
Application Number:	14130481
Application Number:	14130483
Application Number:	14411999
Application Number:	14411978
Application Number:	15055613
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(612)455-3801
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	(612) 455-3800
<b>Email:</b>	mwilkie@hsml.com
<b>Correspondent Name:</b>	HAMRE, SCHUMANN, MUELLER & LARSON, P.C.
<b>Address Line 1:</b>	45 SOUTH SEVENTH STREET
<b>Address Line 2:</b>	SUITE 2700
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	20671.00000001
<b>NAME OF SUBMITTER:</b>	RONG YANG
<b>SIGNATURE:</b>	/rongcyang/
<b>DATE SIGNED:</b>	06/12/2019

PATENT

**Total Attachments: 3**

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**Verification of Translation**

I, GUAN, Mengyun, of 21/F, Bldg. No.3, Xunmei Technology Plaza, Keyuan Avenue, High-Tech Park, Nanshan District, Shenzhen 518057, P. R. China hereby declare that:

1. I am conversant with both the Chinese and English languages;  
and
2. I translated the attached English document from the Chinese language.

I hereby certify that the attached document is the true and accurate translation of the Declaration for Merger between CSMC TECHNOLOGIES FAB2 CO., LTD. and CSMC TECHNOLOGIES FAB1 CO., LTD.

Signature of Translator: Mengyun Guan Date: 2019.6.25

## **Declaration**

The Merger Agreement is made on this 27<sup>th</sup> day of May, 2017 by and between CSMC TECHNOLOGIES FAB2 CO., LTD. and CSMC TECHNOLOGIES FAB1 CO., LTD.. The designated date for merger is on this 4<sup>th</sup> of August, 2017, and hereby, CSMC TECHNOLOGIES FAB2 CO., LTD. continues to exist, CSMC TECHNOLOGIES FAB1 CO. dissolved; all the assets and liabilities of CSMC TECHNOLOGIES FAB1 CO., LTD. are assumed by CSMC TECHNOLOGIES FAB2 CO., LTD..

Executed as of the date set forth below:

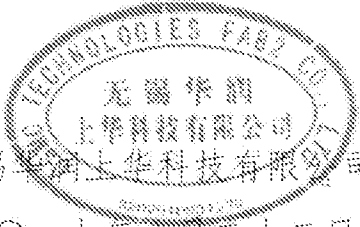
CSMC TECHNOLOGIES FAB2 CO.,  
LTD. (Stamped)  
Date: 2017-8-22

Market Supervision Administration of  
Wuxi (Stamped)  
Date: 2017-8-31

# 说 明

2017年5月27日，无锡华润上华科技有限公司与无锡华润上华半导体有限公司签署《公司合并协议》，2017年8月4日，办理完吸收合并。吸收合并完成后，无锡华润上华科技有限公司存续，无锡华润上华半导体有限公司注销，无锡华润上华半导体有限公司所有的资产、负债由合并后存续的无锡华润上华科技有限公司承继。

特此说明。

  
无锡华润上华科技有限公司  
二〇一七年八月二十二日

